

IN THE SPECIFICATION

Page 1, before the first line, insert, --This Application is a continuation of application
A1 serial no. 08/497,382, filed June 29, 1995.
Now US Patent pending

A1
Am 11-18
Page 3, line 16, kindly delete "or water".

IN THE CLAIMS

Kindly cancel claims 1-16.

Kindly add the following new claims:

Am 11-18
A2 17. A polisher having the ability to measure the thickness of a top layer of a wafer,
the polisher comprising:
 a polishing unit which polishes said top layer in the presence of a liquid;
 an optical measurement station, mounted within said polisher but apart from
 said polishing unit; and
 means to move said wafer from said polishing unit to said optical measurement
 station while said wafer is still wet;
 wherein said optical measurement station comprises;
 a liquid holding unit having a window in a bottom surface thereof and holding
 liquid therein which receives said wafer; and
 an optical thickness measuring unit located on a non-liquid side of said
 window which measures the thickness of said top layer while said wafer is immersed
 in said liquid.